

Data sheet acquired from Harris Semiconductor SCHS032A - Revised March 2002

CD4027B Types

CMOS Dual J-K **Master-Slave Flip-Flop**

High-Voltage Types (20-Volt Rating)

■ CD4027B is a single monolithic chip integrated circuit containing two identical complementary-symmetry J-K masterslave flip-flops. Each flip-flop has provisions for individual J, K, Set, Reset, and Clock input signals. Buffered Q and \overline{Q} signals are provided as outputs. This inputoutput arrangement provides for compatible operation with the RCA-CD4013B dual Dtype flip-flop.

The CD4027B is useful in performing control, register, and toggle functions. Logic levels present at the J and K inputs along with internal self-steering control the state of each flip-flop; changes in the flip-flop state are synchronous with the positivegoing transition of the clock pulse. Set and reset functions are independent of the clock and are initiated when a high level signal is present at either the Set or Reset input.

The CD4027B types are supplied in 16-lead hermetic dual-in-line ceramic packages (D and F suffixes), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline package (NSR suffix), and in chip form (H suffix).

Features:

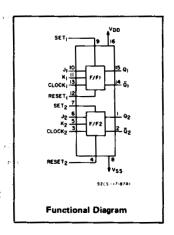
- Set-Reset capability
- Static flip-flop operation retains state indefinitely with clock level either "high" or "low"
- Medium speed operation 16 MHz (typ.) clock toggle rate at 10 V
- Standardized symmetrical output characteristics
- 100% tested for quiescent current at 20 V
- Maximum input current of 1 µA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
- Noise margin (over full packagetemperature range):

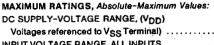
1 V at VDD = 5 V 2 V at VDD = 10 V

- 2.5 V at VDD = 15 V ■ 5-V, 10-V, and 15-V parametric ratings
- Meets all requirements of JEDEC Tentative Standard No. 138, "Standard Specifications for Description of 'B' Series CMOS Devices"

Applications:

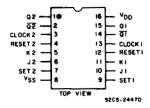
Registers, counters, control circuits



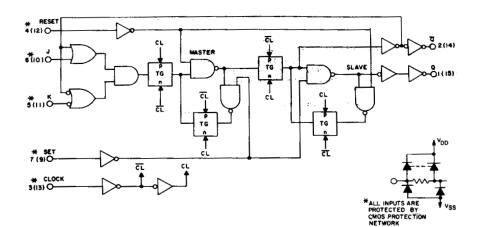


DO 001.151 1051.1051
Voltages referenced to VSS Terminal)0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS0.5V to V _{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT
POWER DISSIPATION PER PACKAGE (PD):
For TA = -55°C to +100°C 500mW
For T _A = +100°C to +125°C Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
FOR TA = FULL PACKAGE-TEMPERATURE RANGE (All Package Types)
OPERATING-TEMPERATURE RANGE (TA)55°C to +125°C
STORAGE TEMPERATURE RANGE (T _{stg})65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):

At distance 1/16 \pm 1/32 inch (1.59 \pm 0.79mm) from case for 10s max+265°C



TERMINAL ASSIGNMENT



	PRE	SEN	IT S	TATE		NEXT STATE				
INPUTS OUTPUT					CL.	OUTPUTS				
٦	Ķ	`\$	R	Ö		0	ō			
1	×	0	0	٥		-	0			
×	0	.0	0	1	\checkmark	t	0			
0	×	٥	0	٥	/	0	ı			
×		0	0			0	ī			
x	×	0	0	×	/		Г	- NO CHANGE		
x	×	1	٥	×	×	-	0			
×	×	0	ī	×	×	0	1			
x	x	1	Т	×	x	-	ī			
LO	GIC	0.1	LOW	LEVEL LEVEL HANGE				92CM-275511		

Fig.1 - Logic diagram and truth table for CD4027B (one of two identical J-K flip flops).

RECOMMENDED OPERATING CONDITIONS at $T_A = 25^{\circ}$ C, Except as Noted. For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V _{DD}	LIA A Paci	UNITS		
	(V)	Min.	Max.		
Supply-Voltage Range (For T _A = Full Package Temperature Range)	-	3	18	v	
	5	200	_		
Data Setup Time ts	10	75	_	ns	
	15	50	· _		
	5	140	_		
Clock Pulse Width tw	10	60	_	ns	
	15	40			
·	5		3.5		
Clock Input Frequency (Toggle Mode) fCL	10	dc	8	MHz	
	15		12		
· ·	5		45		
Clock Rise or Fall Time t _r CL*, t _f CL	10	-	. 5	μς	
	. 15		2		
	5	180	_		
Set or Reset Pulse Width tw	10	80	_	ns	
	15	50			

^{*} If more than one unit is cascaded in a parallel clocked operation, t_rCL should be made less than or equal to the sum of the fixed propagation delay time at 15 pF and the transition time of the output driving stage for the estimated capacitive load.

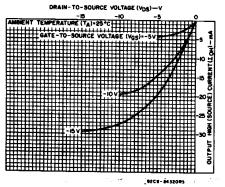


Fig.4 - Typical output high (source) current characteristics.

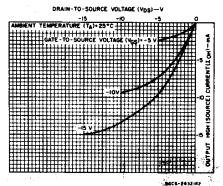


Fig.5 — Minimum output high (source) current characteristics.

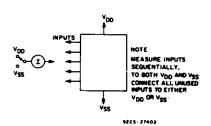


Fig.7 - Input current test circuit.

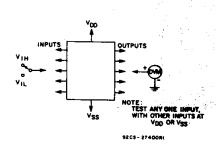


Fig.8 - Input-voltage test circuit.

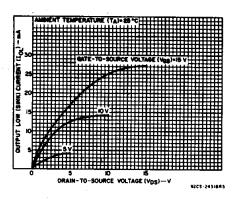


Fig.2 — Typical output low (sink) current characteristics.

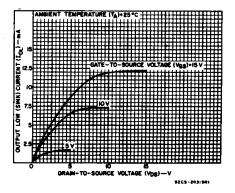


Fig.3 — Minimum output low (sink) current characteristics.

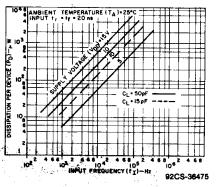


Fig.6 - Typical power dissipation vs. frequency.

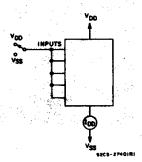
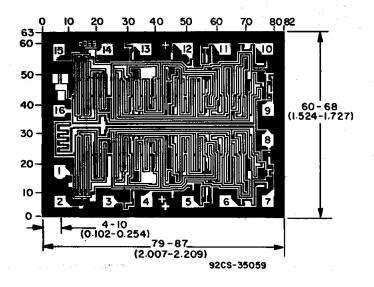


Fig.9 - Quiescent device current test circuit.

CD4027B Types

STATIC ELECTRICAL CHARACTERISTICS

CHARAC- TERISTIC	CON	DITIO	vs	LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
TERISTIC	Vo	VIN	V _{DD}		>		Ι		+25	<u>-, </u>	
	(V)	(V)	(V)	55	-40	+85	+125	Min.	Тур.	Max.	1
Quiescent		0,5	5	1	1	30	30	_	0.02	1	
Device		0,10	10	2	2	60	60	_	0.02	2	
Current		0,15	15	4	4	120	120	_	0.02	4	μΑ
IDD Max.		0,20	20	20	20	600	600	_	0.04	20	
Output Low		†	-					-			
(Sink)	0.4	0,5	5	0.64	0.61	0.42	0.36	0.51	1	_	
Current,	0.5	0,10	10	1.6	1.5	1.1	0.9	1.3	2.6	_	
IOL Min.	1.5	0,15	15	4.2	4	2.8	2.4	3.4	6.8		_
Output High	4.6	0,5	5	-0.64	-0.61	-0.42	-0.36		_1	_	mA
(Source)	2.5	0,5	5	-2	-1.8	-1.3	-1.15	-1.6	-3.2	_	
Current,	9.5	0,10	10	-1.6	-1.5	-1.1	-0.9	-1.3	-2.6		
IOH Min.	13.5	0,15	15	-4.2	4	-2.8	-2.4	-3.4	-6.8		
Output Volt-						· · · ·	·				
age:	L	0,5	5		0.0)5		l –	0	0.05	
Low-Level.		0,10	10		0.0)5			0	0.05	
VOL Max.	_	0,15	15		0.0)5		_	0	0.05	
Output Volt-							•		-	<u> </u>	٧
age:	<u> </u>	0,5	5		4.9)5		4.95	5	_	1.
High-Level,	_	0,10	10		9.9	95		9.95	10		
VOH Min.	_	0,15	15		14.	95	-	14.95	15		
Input Low	0.5,4.5		5		1.	5		_	::	1.5	
Voltage,	1,9	_	10						3		
VIL Max.	1.5,13.5	-	15	4 _							4
Input High	0.5,4.5	_	5		3.	5		3.5			V
Voltage,	1,9		10		7			7	. –		
V _{IH} Min.	1.5,13.5		15		1			11	_	-	-
Input Current, IN Max.	-	0,18	18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μА



Dimensions in millimeters are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3}) .

Dimensions and Pad Layout for CD4027BH

DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 25°C; Input t_r, t_f = 20 ns, C_L = 50 pF, R_L = 200 k Ω

CHARACTERISTIC	VDD	A	UNITS		
	(V)	Min.	Тур.	Max.	
Propagation Delay Time:	5	_	. 150	300	
Clock to \mathbf{Q} or $\overline{\mathbf{Q}}$ Outputs	10		65	130	ns
^t PHL ^{, t} PLH	15	-	45	90	
	5	_	150	300	
Set to Q or Reset to Q tpLH	10	_	65	130	ns
_	15	l –	45	90	
	5	-	200	400	
Set to $\overline{\mathbf{Q}}$ or Reset to \mathbf{Q} tpHL	10	-	85	170	ns
	15		60	120	
	5		100	200	
Transition Time tTHL, tTLH	10		50	100	ns
<u> </u>	15		40	80	·
Maximum Clock Input	5	3.5	7		
Frequency# (Toggle Mode)	10	8	16	_	MHz
fCL	15	12	24		ļ ·
	5	_	70	140	
Minimum Clock Pulse Width tw	10	-	30	60	ns
	15	_	20	40	
Minimum Set or Reset Pulse	5	_	.90	180	
Width tw	10	-	40	80	ns
· · · · · · · · · · · · · · · · · · ·	15	_	25	50	
	5		100	200	
Minimum Data Setup Time t _S	10	-	35	75	ns
	15		25	50	
Clock Input Rise or Fall Time	5			45	
•	10	-	-	5	μs
t _{rCL} , t _{fCL}	15			2	L
Input Capacitance C _I		-	5	7.5	pF

Input t_r , $t_f = 5$ ns.

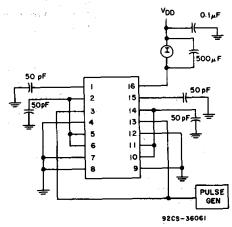


Fig. 13—Dynamic power dissipation test circuit.

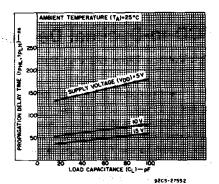


Fig. 10 — Typical propagation delay time vs. load capacitance (CLOCK or SET to Q, CLOCK or RESET to \overline{Q} .

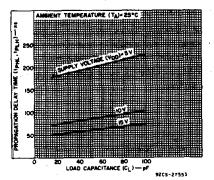


Fig.11 — Typical propagation delay time vs. load capacitance (SET to Q or RESET to Q).

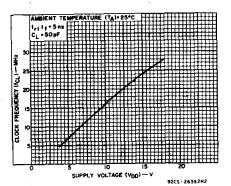


Fig. 12 — Typical maximum clock frequency vs. supply voltage (toggle mode).

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Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265

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